

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

J1046 U.S. PRO
09/848140
05/03/01


Patent Application of Hideyo Esanai et al.

Title: *Metal-Ceramic Circuit Board and Manufacturing Method Thereof*

Attorney Docket: 134.136

Customer No.: 023907

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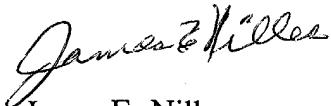
INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This information disclosure statement is being submitted simultaneously with the filing of the above application under the provisions of 37 C.F.R. § 1.97 and § 1.98. Form PTO-1449 and copies of the listed references are enclosed.

Respectfully submitted,



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Dated: May 3, 2001

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